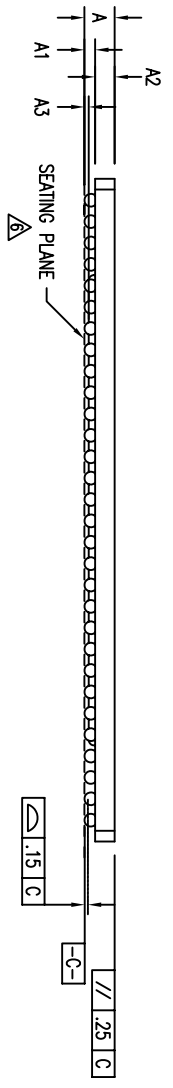
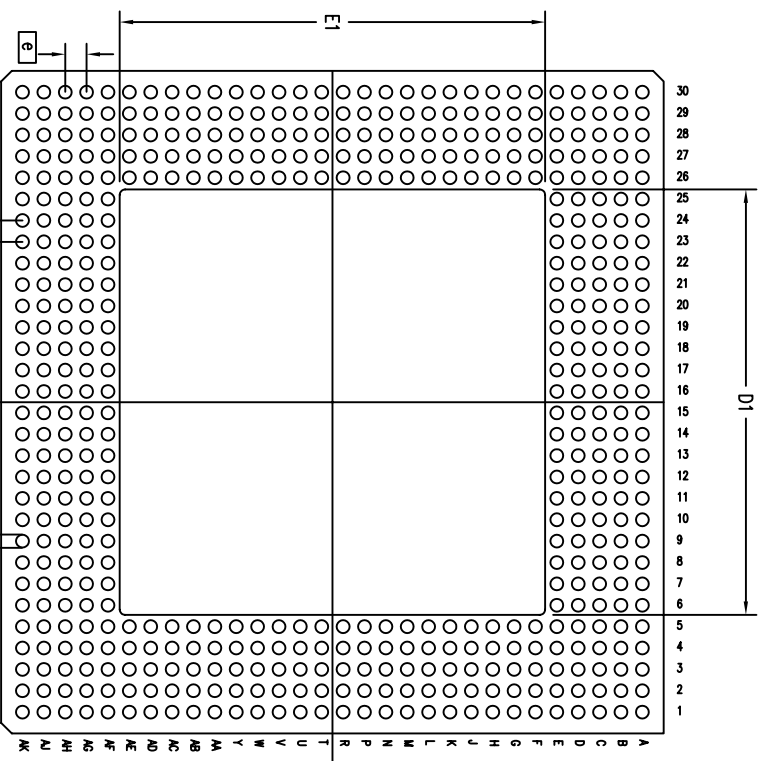
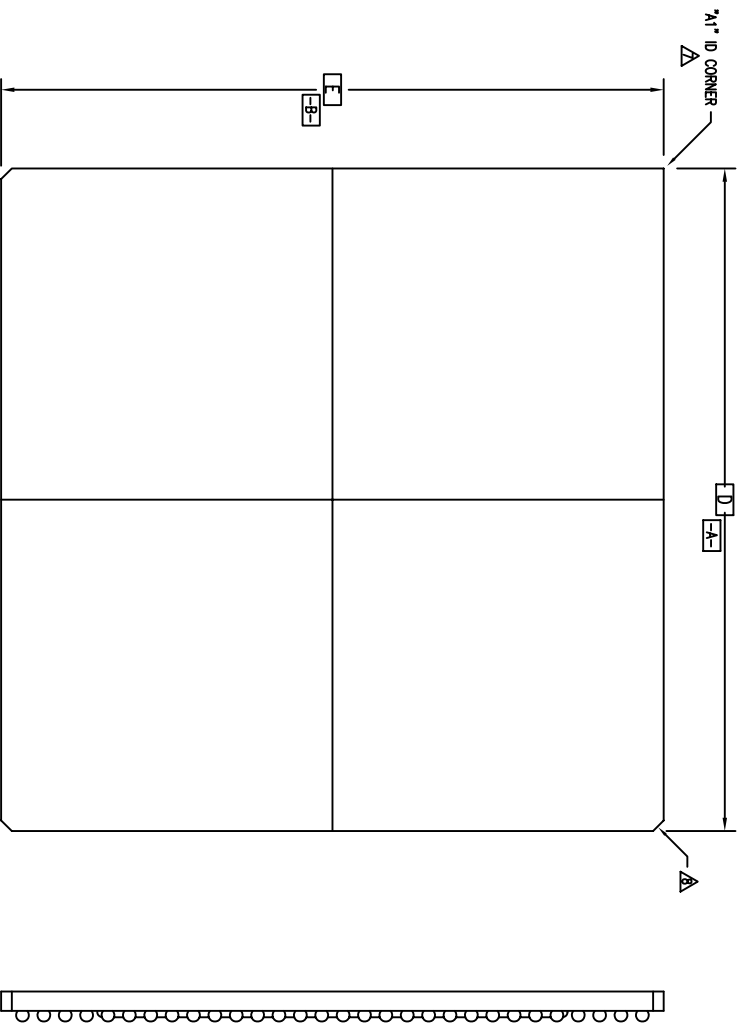

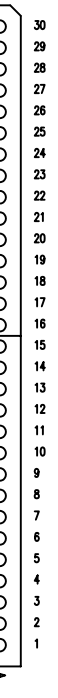


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	04/03/06	DP
01	UPDATE COPLANARITY	10/04/07	DP
02	COMBINE POD & LAND PATTERN	06/13/13	KS



TOLERANCES UNLESS SPECIFIED	
DECIMAL	ANGULAR
XXX±	±
XXXX±	
APPROVALS	DATE
DRAWN <i>DP</i>	04/03/06
CHECKED	
TITLE BX/BXG/RX 500 PACKAGE OUTLINE	
31.0 X 31.0 mm BODY	
1.0 mm BALLPITCH S8GA	
SIZE C	DRAWING No. PSC-4186
DO NOT SCALE DRAWING	REV 02
SHEET 1 OF 3	


**Integrated Device Technology, Inc.**  
 www.idt.com 6024 Silver Creek Valley Road  
 PHONE: (408) 284-8200  
 FAX: (408) 284-8591



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	04/03/06	DP
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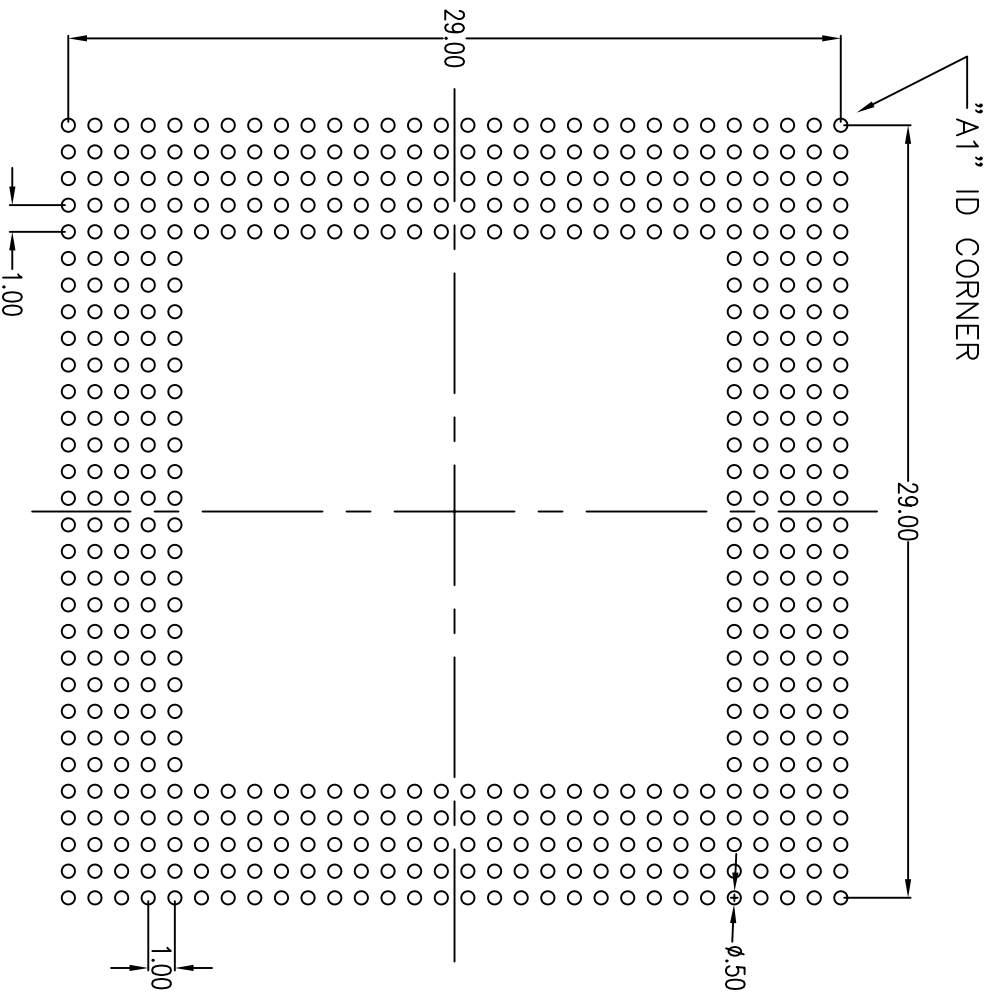
NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- 2 "e" REPRESENTS THE BASIC SOLDER BALL GRID PITCH
- 3 "M" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE
- 4 "N" REPRESENTS THE BALLCOUNT NUMBER
- 5 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM  $\text{---C---}$
- 6 SEATING PLANE AND PRIMARY DATUM  $\text{---C---}$  ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
- 7 "A1" ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON PACKAGE BODY
- 8 EXACT SHAPE OF EACH CORNER IS OPTIONAL
- 9 ALL DIMENSIONS ARE IN MILLIMETERS

SYMBOL	JEDEC VARIATION			NOTE
	MIN	NOM	MAX	
A	—	—	1.70	
A1	.30	—	—	
A2	.25	—	1.10	
A3	.15	—	—	
D	31.00 BSC			
D1	—	—	19.9	
E	31.00 BSC			
E1	—	—	19.9	
M	30 (DEPOPULATED)			3
N	500			4
e	1.00 BSC			
b	.50	.60	.70	5
CENTER BALL MATRIX	N/A			

<b>TOLERANCES UNLESS SPECIFIED</b> DECIMAL ANGULAR XXXX ± XXXX ±		<b>ITD™ Integrated Device Technology, Inc.</b> 6024 Silver Creek Valley Road WWW.ITD.COM PHONE: (408) 284-8200 FAX: (408) 284-8591	
APPROVALS	DATE	TITLE	REV
DRAWN <b>JP</b>	04/03/06	BX/BXG/RX 500 PACKAGE OUTLINE	02
CHECKED		31.0 X 31.0 mm BODY 1.0 mm BALLPITCH SBCA	
		SIZE DRAWING NO. PSC-4186	
		DO NOT SCALE DRAWING	SHEET 2 OF 3

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	04/03/06	DP
01	UPDATE COPLANARITY	10/04/07	DP
02	COMBINE POD & LAND PATTERN	06/13/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		<b>IDTV</b> Integrated Device Technology, Inc. 6024 Silver Creek Valley Road www.idtv.com PHONE: (408) 284-8200 FAX: (408) 284-8591	
DECIMAL	ANGULAR		
XXX±	±		
XXXX±			
APPROVALS	DATE	TITLE	
DRAWN <b>JP</b>	04/03/06	BX/BXG/RX 500 PACKAGE OUTLINE	
CHECKED		31.0 X 31.0 mm BODY	
		1.0 mm BALLPITCH SBGA	
SIZE	DRAWING No.	REV	
<b>C</b>	PSC-4186	<b>02</b>	
DO NOT SCALE DRAWING		SHEET	3 OF 3